

Crystal OSCILLATOR

2.0X1.6 MM Surface Mount Package



Approved by:
Checked by:
Issued by:

SPECIFICATION

P/N: 1N500000DC0XMBL

深圳市晶科鑫实业有限公司
SHENZHEN CRYSTAL TECHNOLOGY INDUSTRIAL CO., LTD.

Tel: 86-755-88352809
E-mail: sjksale@126.com

Fax: 86-755-88353718
URL: [Http://www.q-crystal.com](http://www.q-crystal.com)

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FEATURE

- Compact and thin ceramic package with metalized surface mounting and automatically loaded
- Reflow solder is possible
- Lower noise and current with reduced power consumption
- Built-in C-MOS IC with tri-state function

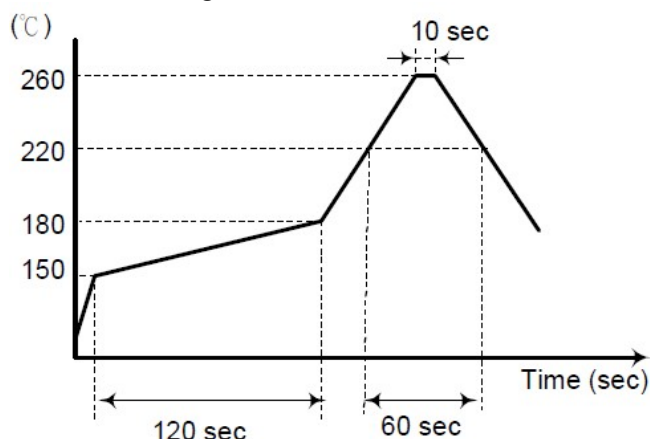
ELECTRICAL SPECIFICATIONS

Parameters	Condition/Model	
Fan Out Type		HCMOS
Supply Voltage		1.8~3.3V $\pm 10\%$
Frequency		50.000MHz
Operating Temperature		-40°C ~ +85°C
Input Current	Frequency Range	5mA max
Frequency Stability	All Conditions	± 25 ppm
Symmetry	AT 1/2 Vdd	45/55%
Output Voltage	Vol(max)	10% Vdd
	VoH(min)	90% Vdd
Rise/Fall Time	AT 0.1Vdd~0.9Vdd	10ns Max
Driving Ability	CMOS load max	15pF
Start-up Time	Load RANGE	10ms max
E/D Function	#1 OPEN	PIN #3 ACTIVE
	#1 $\geq 70\%$ Vdd	PIN #3 ACTIVE
	#1 $\leq 30\%$ Vdd	PIN #3 HighZ
PAD Connection		PIN#1 E/D PIN#3 OUT
		PIN#2 GND PIN#4 Vdd

Reflow Soldering Profile

Total Time: 200 sec. Max.

Solder Melting Point :220 °C



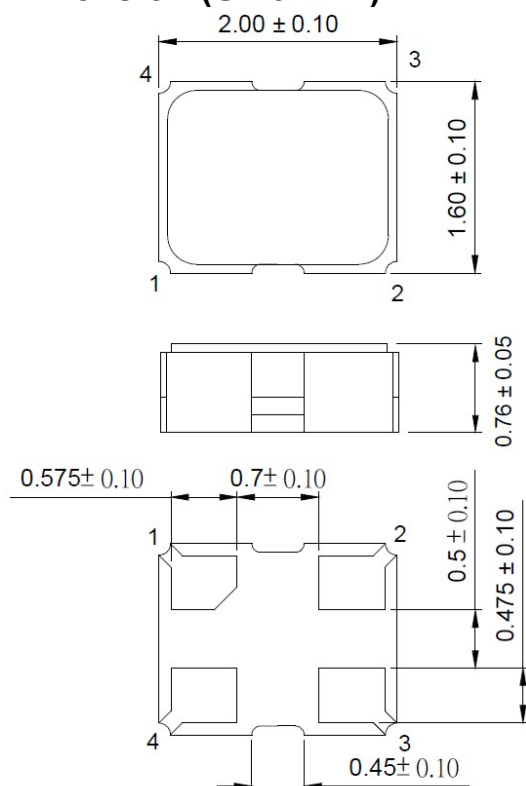
The design, manufacturing process, and specifications of this device are subject to change without notice.

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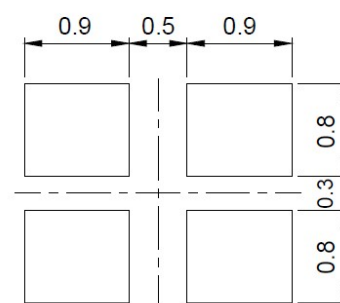


Dimension (Unit: mm)

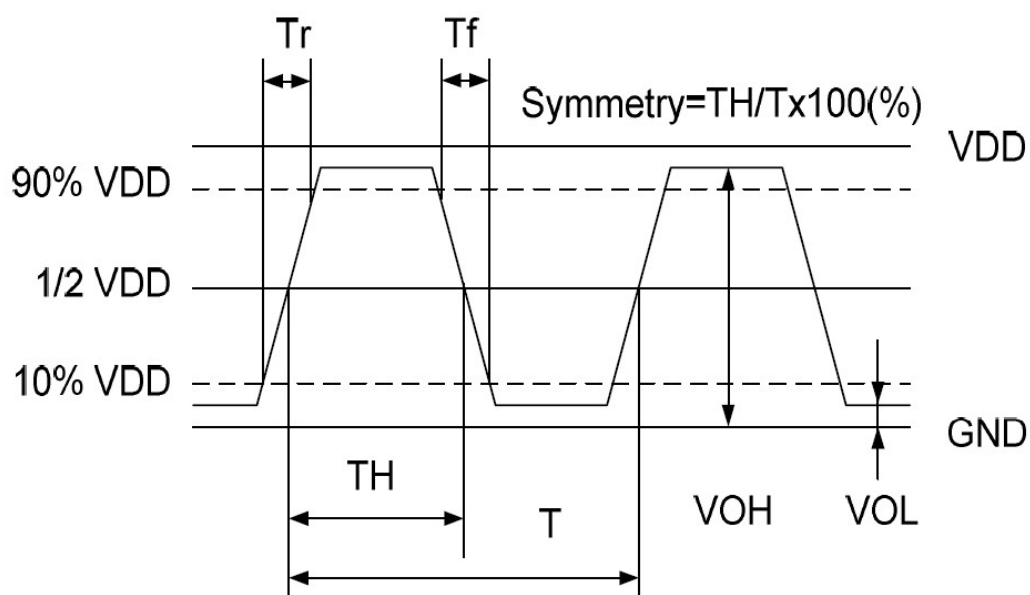


PAD FUNCTION:
1: ENABLE CONTROL
2: GND
3: OUT
4: VDD

Suggested Layout



Waveform Conditions

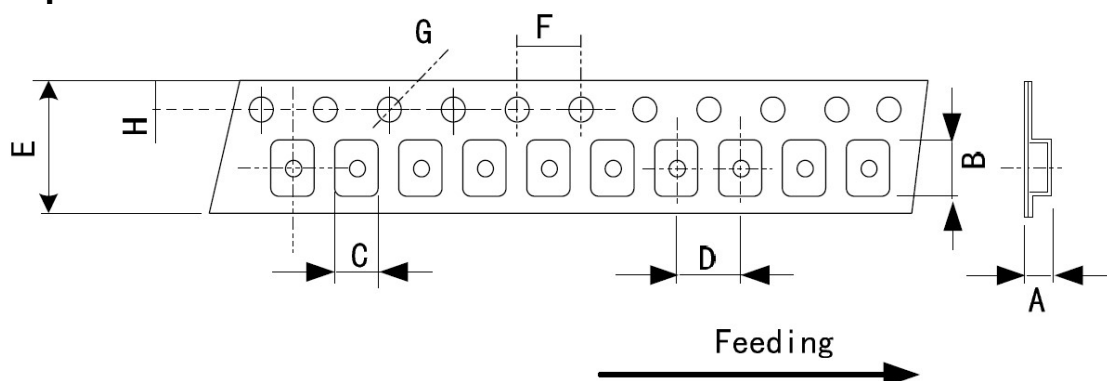


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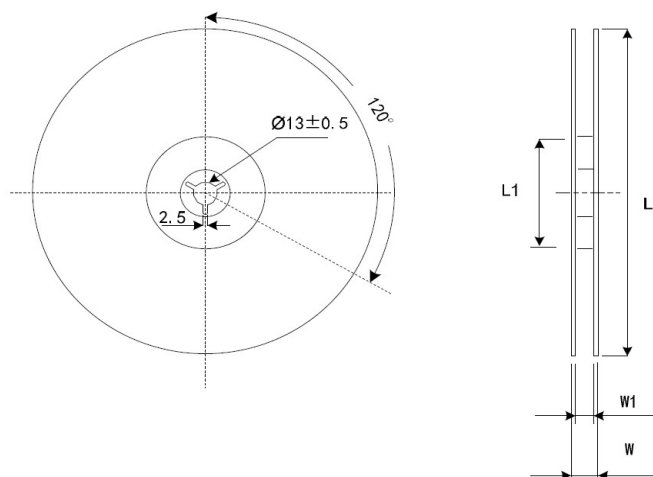
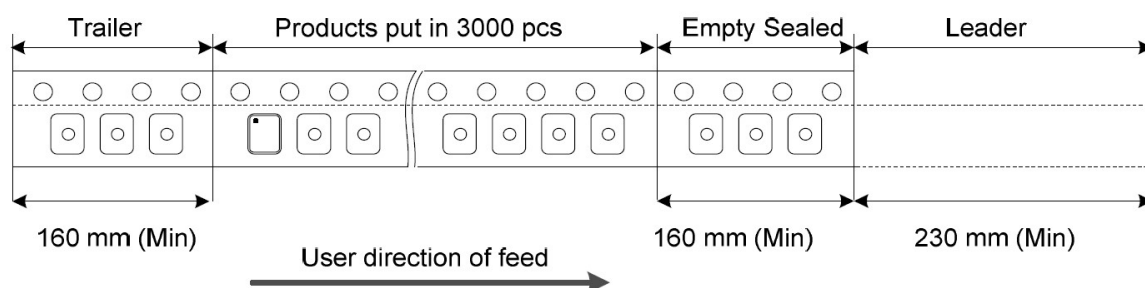


Tape Dimension



	A	B	C	D	E	F	G	H	
DIMENSIONS	0.90 ±0.10	2.30 ±0.10	1.90 ±0.10	4.00 ±0.10	8.00 ±0.20	4.00 ±0.10	1.55 ±0.05	1.75 ±0.10	(UNIT:mm)

REMARK :



	L	L1	W	W1	
DIMENSIONS	178 ±1.00	60.2 ±0.50	11.5 ±0.2	8 +1/-0	Standard Reel Quantity is 3,000 pcs per reel (UNIT:mm)

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